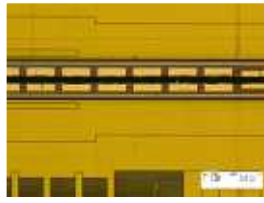
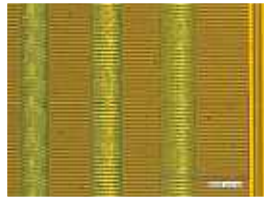


DRAM(full cut with <math>< 25 \mu\text{m}</math> curf)



Removal of resist (linear)



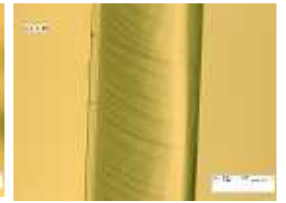
Scribe (SiC)



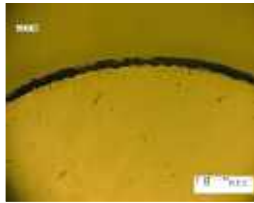
Scribe (sapphire)



Scribed surface for 300 μm GaAs



Shallow scribed surface (glass)



Full cut circular glass



Full cut surface (Kapton)



Polyimide 30 μm



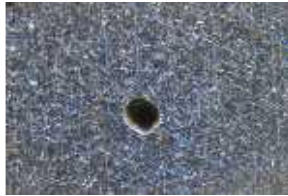
Si 50 μm



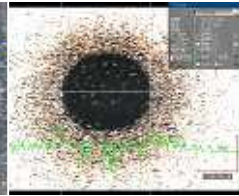
Inbar 30 μm



Stainless hole array 30 μm



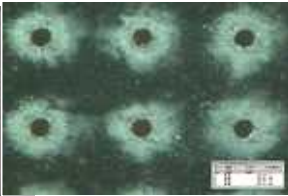
Si 20 μm



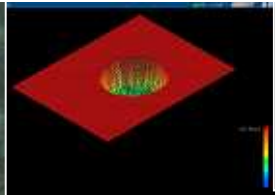
Steel 30 μm



Glass epoxy through hole



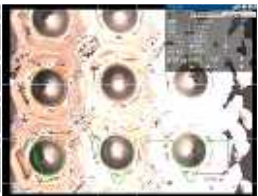
Hole array (LiTaO3)



Polyimide hole on Si substrate



Hole array for Si



Dents on carbon with 6 μm



Color glass dicing



Circular glass



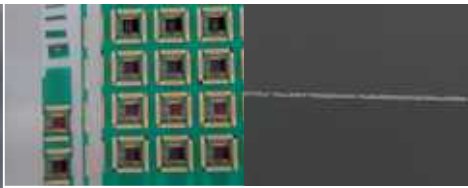
Irregular coated mirror



Fan shape coated glass



Micro electronics



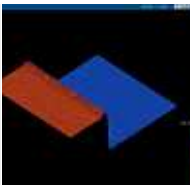
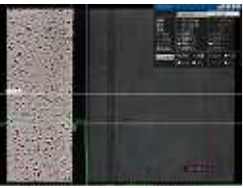
Cut line for 30 μm thin plastic film



Full cut of irregular shape (μSD card)



Criss crossed cut(Si + glass)



Remove (3 μm)



Full cut of ceramic (TiBaO3)



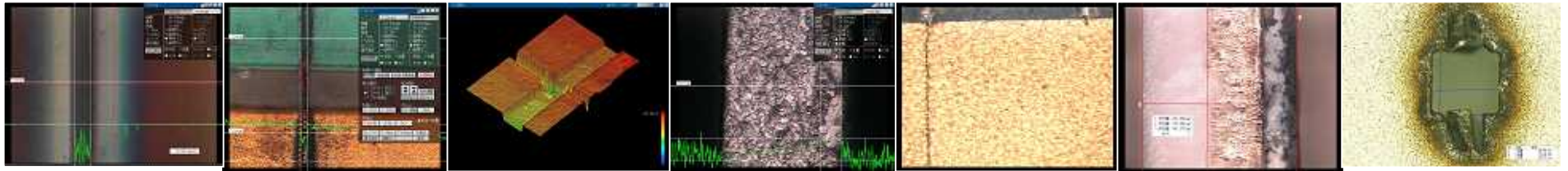
Full cut for super hard ceramics



Bio chip (example for 10 μm)



Micro welding



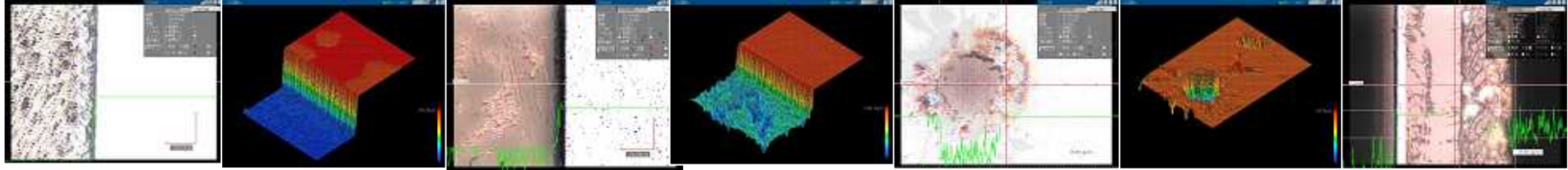
Composite (glass + Si)

Composite (plastics + LED)

Full cut of GaAs(surface)/gold electrode (rear surface)

Alumina composite (cut)

Hole with micro irregular shape



Crip cross cut for Si+glass composite

Drilling of glass on Si substrate

Scribe surface of sapphire

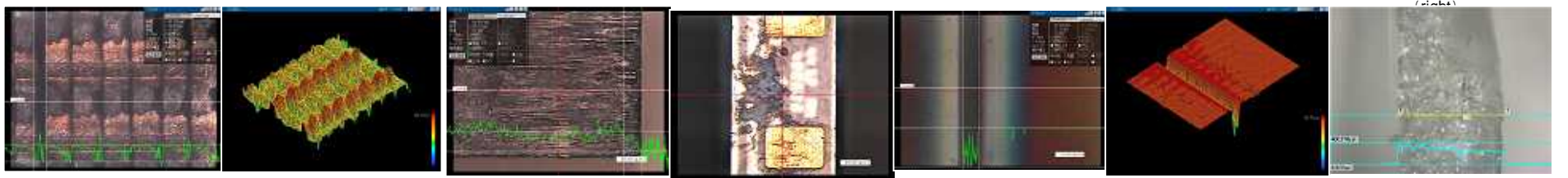


Scribe of GaAs

Tie bar cutting

Sapphire cut/rear surface (cut to rear surface from the front)

Glass removal on ITO surface



Micro welding of stacked micro thin metals

Full cut of ultra hard ceramics chip

Scribe of tempax glass

Surface of full cut of tempax glass



Through hole of electrode on Si substrate

Full cut of sapphire chip

High speed full cut (Si+glass)

Full cut of GaP(cut, surface, front and rear surface)



Scribe of 400 μm sapphire

Micro cleaning (before and after)

Through hole of Si with 400 μm

Dicing of transparent sapphire plate